

terminal, the interposer having at least one electrically conductive interconnect electrically coupling the at least one bond pad of the semiconductor die positioned adjacent to the die attach surface to the at least external terminal positioned adjacent to the external surface; and

*C1*  
*could*  
a plurality of pieces of compliant adhesive film disposed in between the semiconductor die and the interposer to adhere the semiconductor die to the die attach surface of the interposer.

*C2*  
*Sub E2*  
5. (Amended) The package of claim 1 wherein each of the plurality of pieces of compliant adhesive film comprises:

a first adhesive layer adhered to the die attach surface of the interposer;

a second adhesive layer adhered to the semiconductor die; and

at least one compliant carrier layer disposed in between the first and second adhesive layers and to which the first and second adhesive layers are adhered.

6. (Amended) The package of claim 1 wherein each of the plurality of pieces of compliant adhesive film comprises a single layer of elastomer material.

7. (Amended) The package of claim 1 wherein the first surface of the semiconductor die is adhered to the die attach surface of the interposer by the plurality of pieces of compliant adhesive film.

*C3*  
*Sub E3*  
9. (Amended) The package of claim 1 wherein the plurality of pieces of compliant adhesive film comprise strips of compliant adhesive film positioned in parallel along a longitude of the semiconductor die.

10. (Amended) The package of claim 1 wherein a first and a second of the plurality of pieces of compliant adhesive film are positioned at a right angle with respect to each other.

11. (Amended) A device package assembly for a semiconductor die being constructed from a process comprising:

laminating a plurality of pieces of compliant adhesive film to an interposer having at least one electrically conductive interconnect, the interposer further having a die attach surface to which the semiconductor die is attached, and an external surface opposite of the die attach surface;

attaching to the interposer the semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated; and

bonding the at least one electrically conductive interconnect to the at least one electrically conductive bond pad.

17. (Amended) The package assembly of claim 11 wherein each of the plurality of pieces of compliant adhesive film comprises a single layer of elastomer material.

18. (Amended) The package assembly of claim 11 wherein the plurality of pieces of compliant adhesive film comprise strips of film positioned in parallel along a longitude of the semiconductor die.

42. (Amended) A semiconductor device package, comprising:  
a semiconductor die having a first surface on which at least one electrically conductive bond pad is fabricated;

an interposer having a die attach surface and at least one electrically conductive interconnect electrically coupled to at least one bond pad of the semiconductor die; and

a plurality of strips of compliant adhesive film interposed between the die attach surface and the semiconductor die to adhere the semiconductor die to the die attach surface of the interposer.